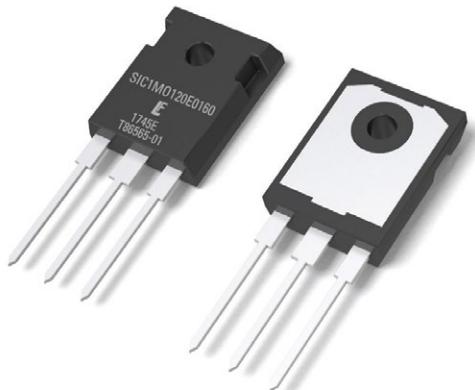


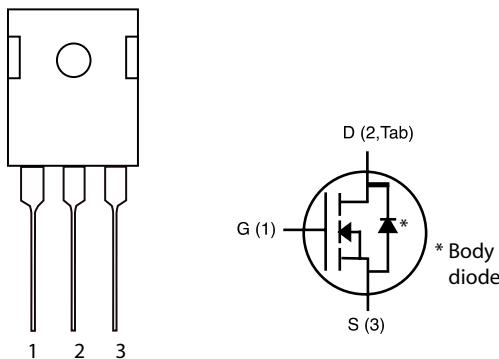
LSIC1MO120E0160 1200 V N-channel, Enhancement-mode SiC MOSFET **HF**



Product Summary

Characteristics	Value	Unit
V_{DS}	1200	V
Typical $R_{DS(ON)}$	160	mΩ
I_D ($T_c \leq 100^\circ\text{C}$)	14	A

Circuit Diagram TO-247-3L



Environmental

- Littelfuse "RoHS" logo = RoHS conform
- Littelfuse "HF" logo = Halogen Free
- Littelfuse "Pb-free" logo = Pb-free lead plating

Features

- Optimized for high-frequency, high-efficiency applications
- Extremely low gate charge and output capacitance
- Low gate resistance for high-frequency switching
- Normally-off operation at all temperatures
- Ultra-low on-resistance

Applications

- High-frequency applications
- Solar Inverters
- Switch Mode Power Supplies
- UPS
- Motor Drives
- High Voltage DC/DC Converters
- Battery Chargers
- Induction Heating

Maximum Ratings

Characteristics	Symbol	Conditions	Value	Unit
Continuous Drain Current	I_D	$V_{GS} = 20\text{ V}, T_c = 25\text{ }^\circ\text{C}$	22	A
		$V_{GS} = 20\text{ V}, T_c = 100\text{ }^\circ\text{C}$	14	
Pulsed Drain Current ¹	$I_{D(\text{pulse})}$	$T_c = 25\text{ }^\circ\text{C}$	44	A
Power Dissipation	P_D	$T_c = 25\text{ }^\circ\text{C}, T_j = 150\text{ }^\circ\text{C}$	125	W
Operating Junction Temperature	T_j		-55 to 150	$^\circ\text{C}$
Gate-source Voltage	$V_{GS,\text{MAX}}$	Absolute maximum values	-6 to 22	V
	$V_{GS,\text{OPTR}}$	Transient, <1% duty cycle	-10 to 25	
	$V_{GS,\text{OP}}$	Recommended DC operating values	-5 to 20	
Storage Temperature	T_{STG}	-	-55 to 150	$^\circ\text{C}$
Lead Temperature for Soldering	T_{sold}	-	260	$^\circ\text{C}$
Mounting Torque	M_D	M3 or 6-32 screw	0.6	Nm
			5.3	in-lb

Footnote 1: Pulse width limited by $T_{j,\text{max}}$

Thermal Characteristics

Characteristics	Symbol	Value	Unit
Maximum Thermal Resistance, junction-to-case	$R_{th,JC,\text{max}}$	1.0	$^\circ\text{C}/\text{W}$
Maximum Thermal Resistance, junction-to-ambient	$R_{th,JA,\text{max}}$	40	$^\circ\text{C}/\text{W}$

Electrical Characteristics ($T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	1200	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 1200\text{ V}, V_{GS} = 0\text{ V}$	-	1	100	μA
		$V_{DS} = 1200\text{ V}, V_{GS} = 0\text{ V}, T_j = 150\text{ }^\circ\text{C}$	-	2	-	
Gate Leakage Current	$I_{GSS,F}$	$V_{GS} = 22\text{ V}, V_{DS} = 0\text{ V}$	-	-	100	nA
	$I_{GSS,R}$	$V_{GS} = -6\text{ V}, V_{DS} = 0\text{ V}$	-	-	100	
Drain-source On-state Resistance	$R_{DS(\text{ON})}$	$I_D = 10\text{ A}, V_{GS} = 20\text{ V}$	-	160	200	$\text{m}\Omega$
		$I_D = 10\text{ A}, V_{GS} = 20\text{ V}, T_j = 150\text{ }^\circ\text{C}$	-	210	-	
Gate Threshold Voltage	$V_{GS,(\text{th})}$	$V_{DS} = V_{GS}, I_D = 5\text{ mA}$	1.8	2.8	4.0	V
		$V_{DS} = V_{GS}, I_D = 5\text{ mA}, T_j = 150\text{ }^\circ\text{C}$	-	1.9	-	
Gate Resistance	R_G	Resonance method, Drain-Source shorted	-	0.95	-	Ω

SiC MOSFET

LSIC1MO120E0160, 1200 V, 160 mOhm, TO-247-3L

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Conditions	Value			Unit
			Min	Typ	Max	
Dynamic Characteristics						
Turn-on Switching Energy	E_{ON}	$V_{DD} = 800 \text{ V}, I_D = 10 \text{ A}, V_{GS} = -5/+20 \text{ V}, R_{G,ext} = 5 \Omega, L = 1.4 \text{ mH}, \text{FWD=LSiC2SD120A05}$	-	77	-	μJ
Turn-off Switching Energy	E_{OFF}		-	59	-	
Total Per-cycle Switching Energy	E_{TS}		-	136	-	
Input Capacitance	C_{ISS}	$V_{DD} = 800 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}, V_{AC} = 25 \text{ mV}$	-	870	-	pF
Output Capacitance	C_{OSS}		-	45	-	
Reverse Transfer Capacitance	C_{RSS}		-	7	-	
C_{OSS} Stored Energy	E_{OSS}		-	14	-	
Total Gate Charge	Q_g	$V_{DD} = 800 \text{ V}, I_D = 10 \text{ A}, V_{GS} = -5/+20 \text{ V}$	-	57	-	nC
Gate-source Charge	Q_{gs}		-	14	-	
Gate-drain Charge	Q_{gd}		-	20	-	
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 800 \text{ V}, V_{GS} = -5/+20 \text{ V}, I_D = 10 \text{ A}, R_{G,ext} = 5 \Omega, R_L = 80 \Omega, \text{Timing relative to } V_{DS}$	-	12	-	ns
Rise Time	t_r		-	8	-	
Turn-off Delay Time	$t_{d(off)}$		-	19	-	
Fall Time	t_f		-	14	-	

Reverse Diode Characteristics

Characteristics	Symbol	Conditions	Value			Unit
			Min	Typ	Max	
Diode Forward Voltage	V_{SD}	$I_S = 5 \text{ A}, V_{GS} = 0 \text{ V}$	-	3.8	-	V
		$I_S = 5 \text{ A}, V_{GS} = 0 \text{ V}, T_J = 150^\circ\text{C}$	-	3.4	-	
Continuous Diode Forward Current	I_S	$V_{GS} = 0 \text{ V}, T_c = 25^\circ\text{C}$	-	-	24	A
Peak Diode Forward Current ¹	I_{SP}		-	-	44	

Footnote 1: Pulse width limited by $T_{J,max}$

Figure 1: Maximum Power Dissipation ($T_J = 150^\circ\text{C}$)

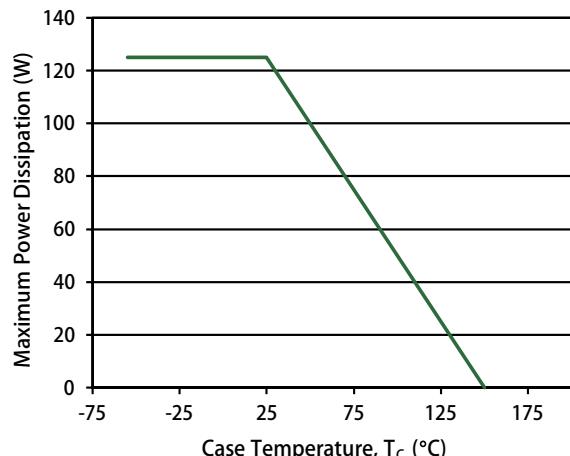


Figure 2: Transfer Characteristics ($V_{DS} = 10\text{ V}$)

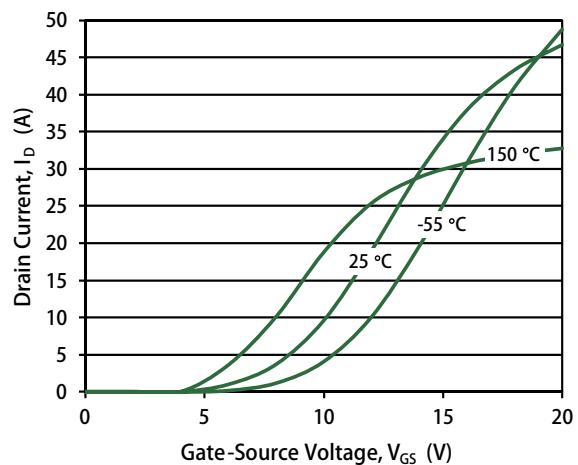


Figure 3: Output Characteristics ($T_J = 25^\circ\text{C}$)

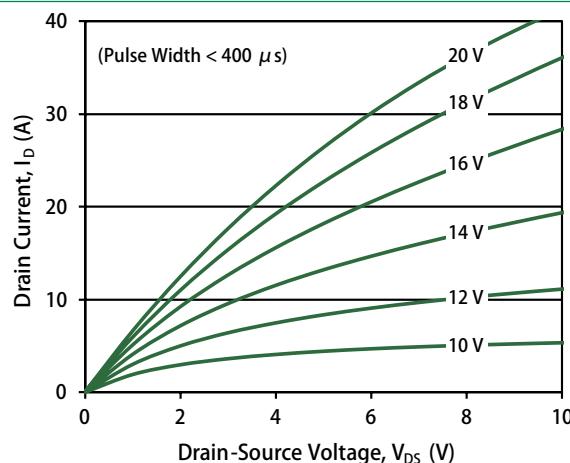


Figure 4: Output Characteristics ($T_J = 150^\circ\text{C}$)

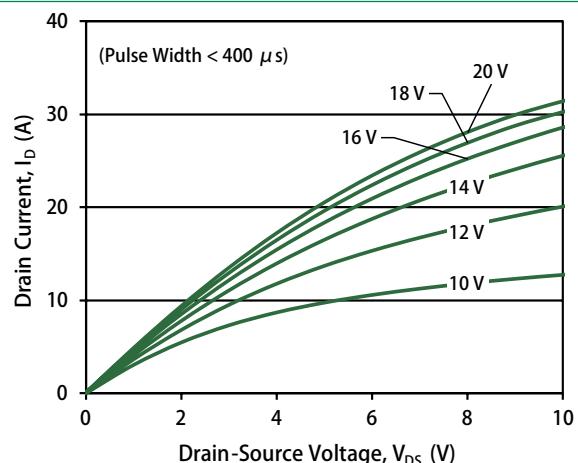


Figure 5: Output Characteristics ($T_J = -55^\circ\text{C}$)

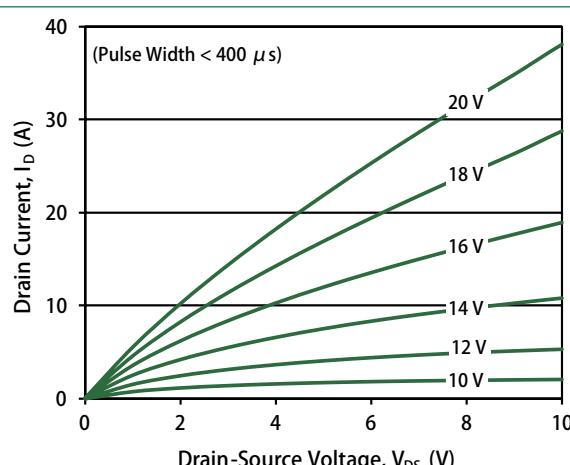


Figure 6: Reverse Conduction Characteristics ($T_J = 25^\circ\text{C}$)

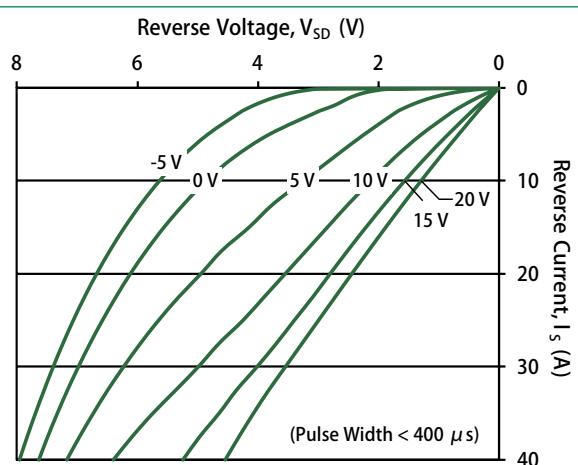


Figure 7: Reverse Conduction Characteristics ($T_J = 150^\circ\text{C}$)

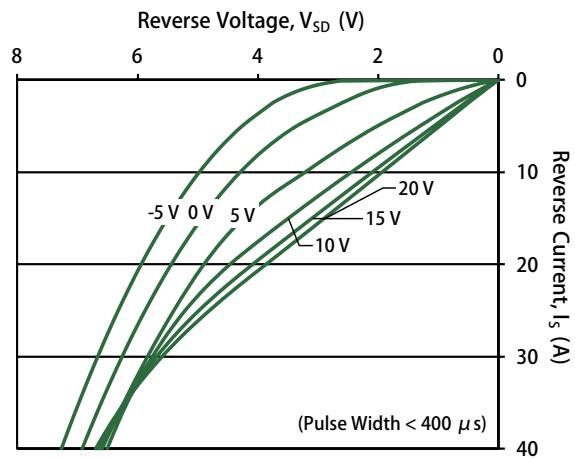


Figure 8: Reverse Conduction Characteristics ($T_J = -55^\circ\text{C}$)

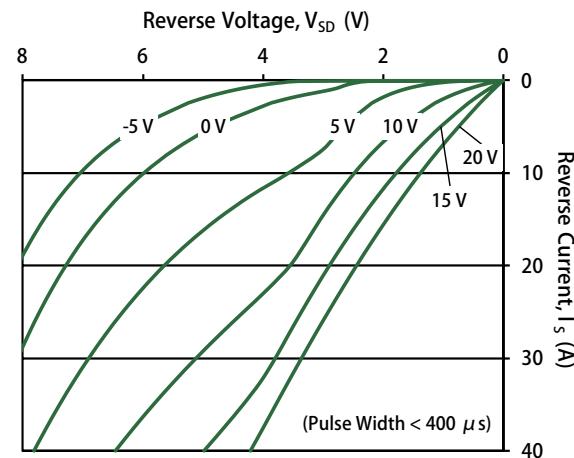


Figure 9: Transient Thermal Impedance

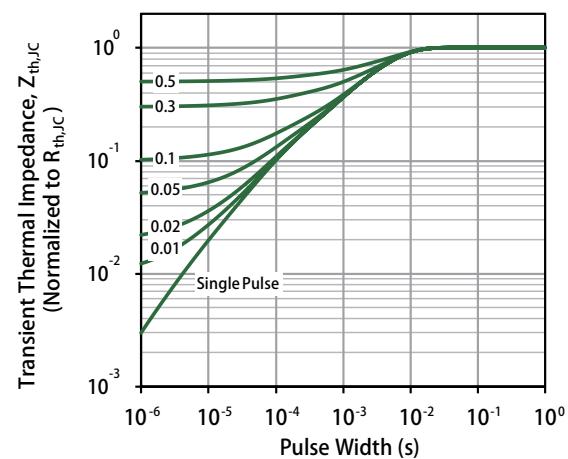


Figure 10: Safe Operating Area ($T_c = 25^\circ\text{C}$)

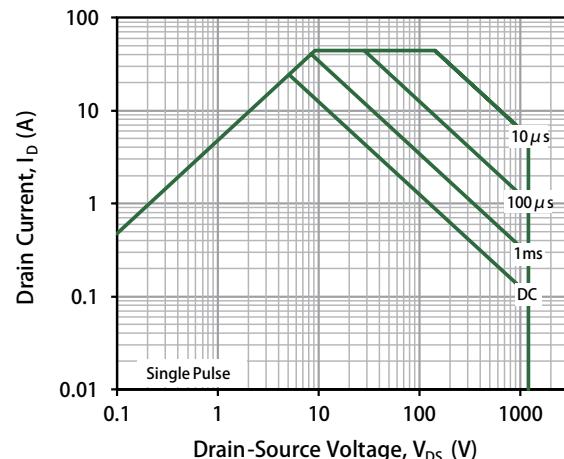


Figure 11: On-resistance vs. Drain Current

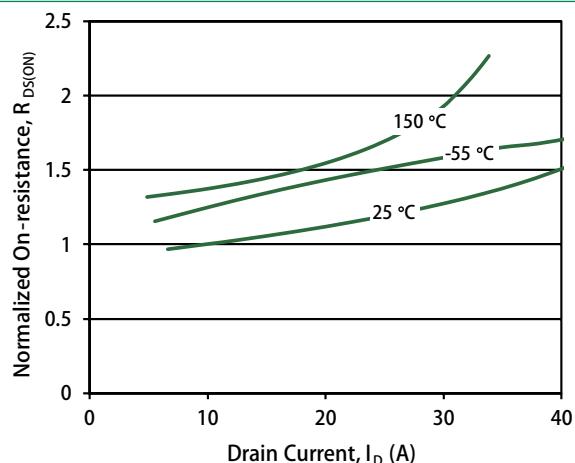


Figure 12: Normalized On-resistance

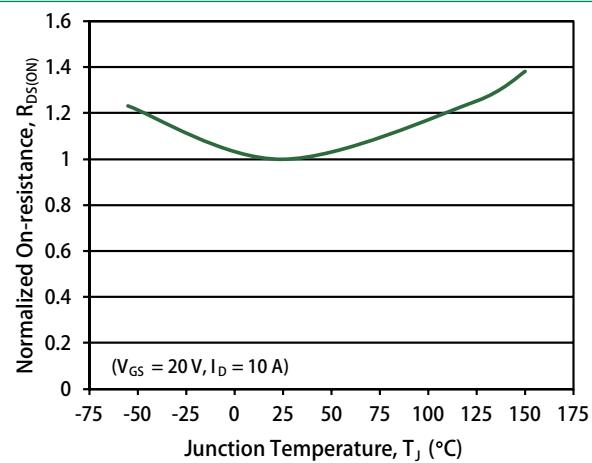


Figure 13: Threshold Voltage

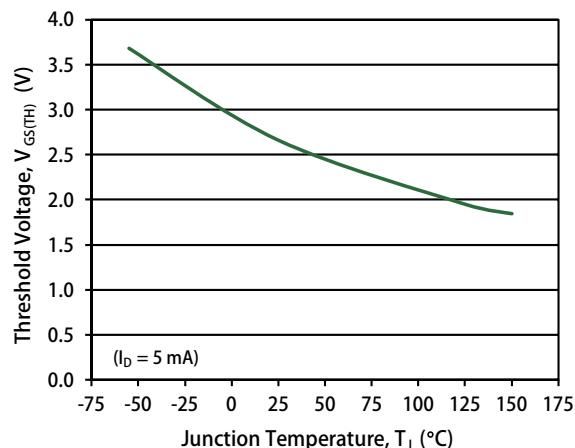


Figure 14: Drain-Source Blocking Voltage

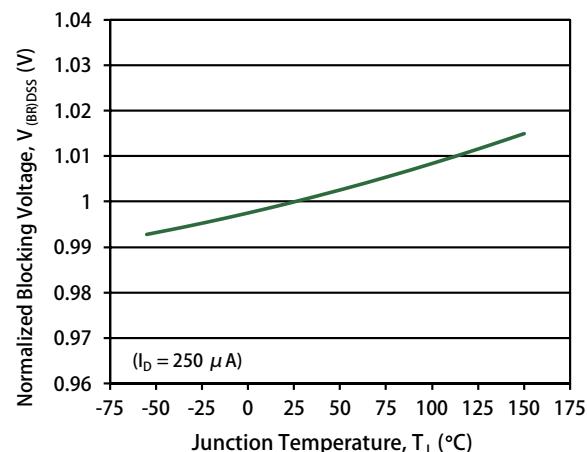


Figure 15: Junction Capacitances

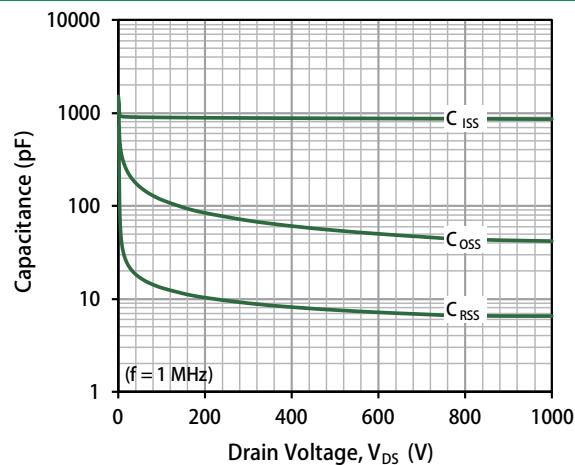


Figure 16: Junction Capacitances

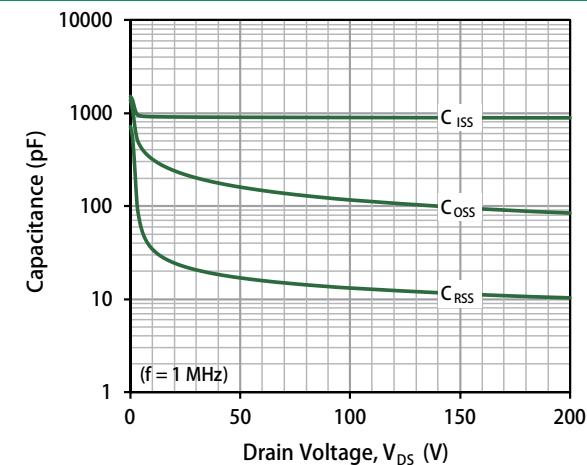


Figure 17: C_{oss} Stored Energy E_{oss}

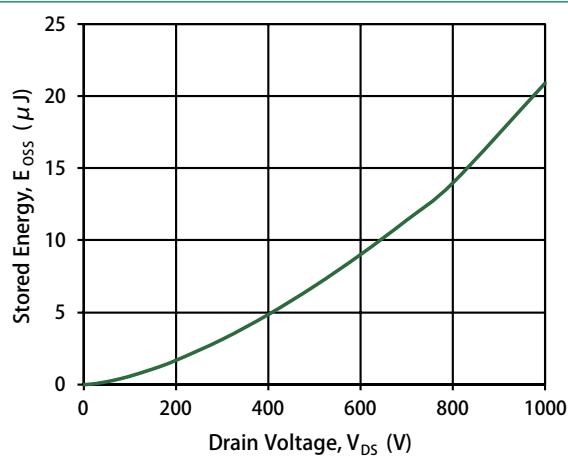


Figure 18: Gate Charge

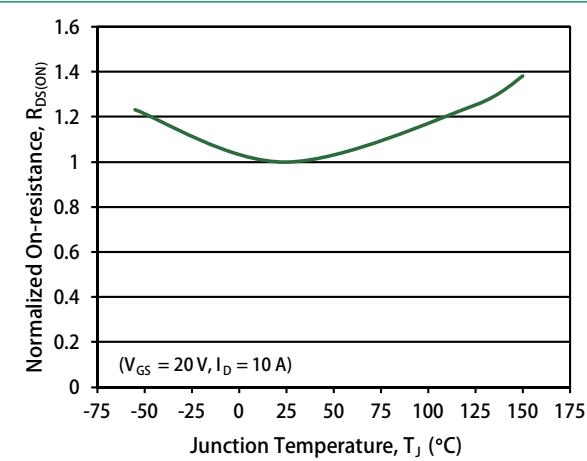


Figure 19: Switching Energy vs. Drain Current

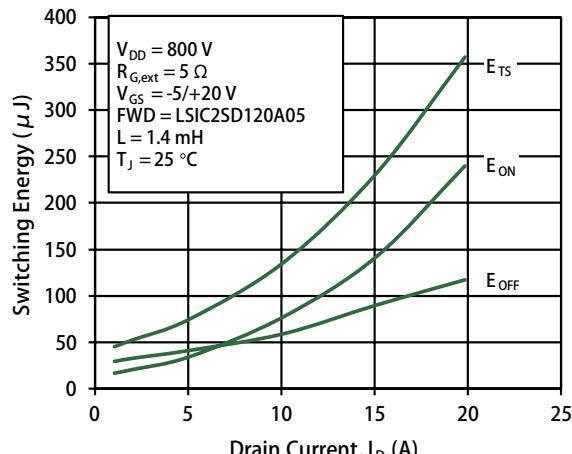
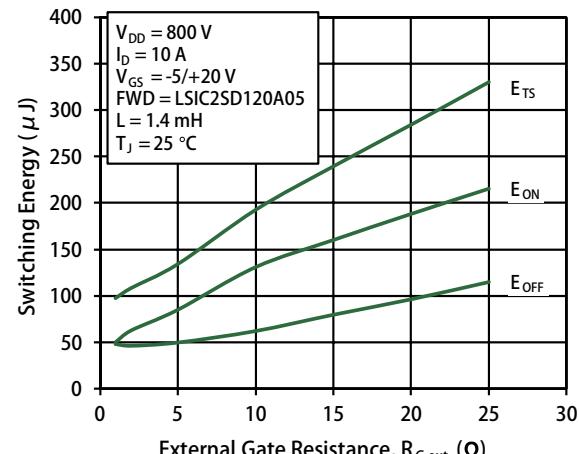
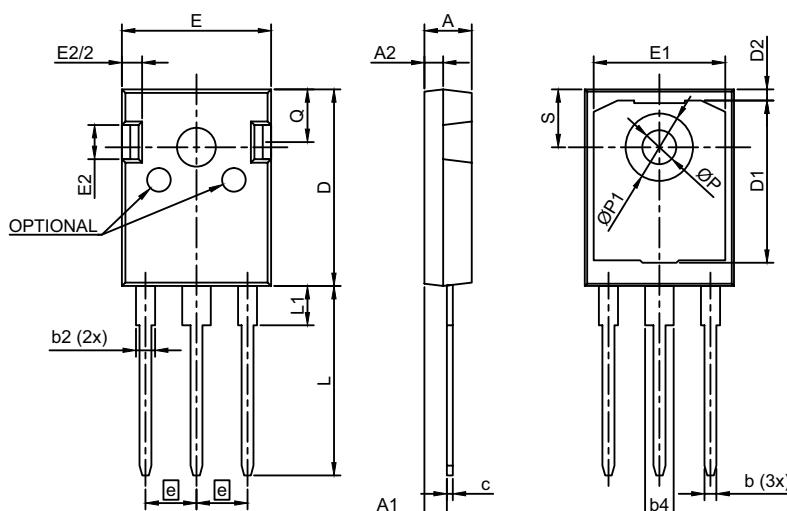


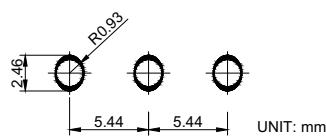
Figure 20: Switching Energy vs. Gate Resistance



Package Dimensions TO-247-3L



Recommended Hole Pattern Layout



Notes:

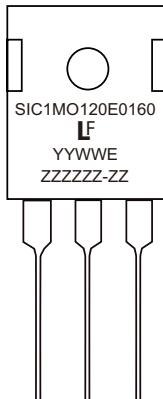
- Dimensions are in millimeters
- Dimension D, E do not include mold flash. Mold flash shall not exceed 0.127 mm per side measured at outer most extreme of plastic body.
- ØP to have a maximum draft angle of 38.1 mm to the top of the part with a maximum hole diameter of 3.912 mm.

Symbol	Millimeters		
	Min	Nom	Max
A	4.80	5.03	5.20
A1	2.25	2.38	2.54
A2	1.85	1.98	2.11
b	0.99	-	1.40
b2	1.65	-	2.39
b4	2.59	-	3.43
c	0.38	0.64	0.89
D	20.80	20.96	21.34
D1	13.50	-	-
D2	0.51	1.19	1.35
e	5.44 BSC		
E	15.75	15.90	16.13
E1	13.06	14.02	14.15
E2	4.19	4.32	4.83
L	19.81	20.19	20.57
L1	3.81	4.19	4.45
ØP	3.55	3.61	3.66
ØP1	7.06	7.19	7.32
Q	5.49	5.61	6.20
S	6.05	6.17	6.30

SiC MOSFET

LSIC1MO120E0160, 1200 V, 160 mOhm, TO-247-3L

Part Numbering and Marking System

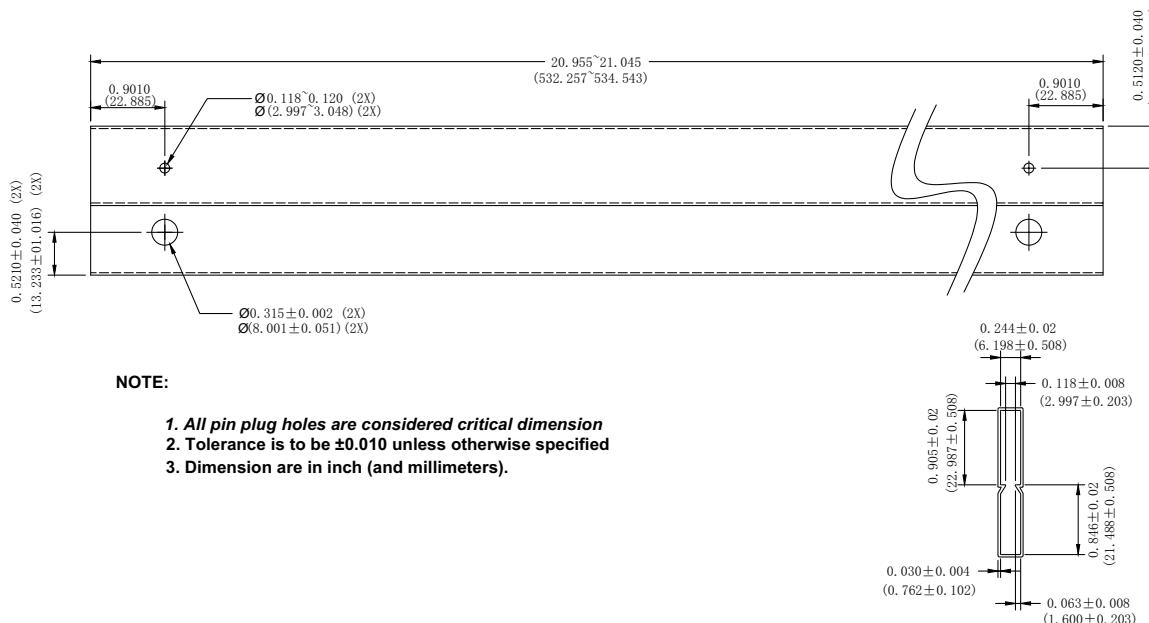


SIC = SiC
 1 = Gen1
 MO = MOSFET
 120 = Voltage Rating (1200 V)
 E = TO-247-3L
 0160 = $R_{DS(ON)}$ (160 mOhm)
 YY = Year
 WW = Week
 E = Special Code
 ZZZZZZ-ZZ = Lot Number

Packing Options

Part Number	Marking	Packing Mode	M.O.Q
LSIC1MO120E0160	SIC1MO120E0160	Tube	450

Packing Specification TO-247-3L



NOTE:

1. All pin plug holes are considered critical dimension
2. Tolerance is to be ± 0.010 unless otherwise specified
3. Dimension are in inch (and millimeters).

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